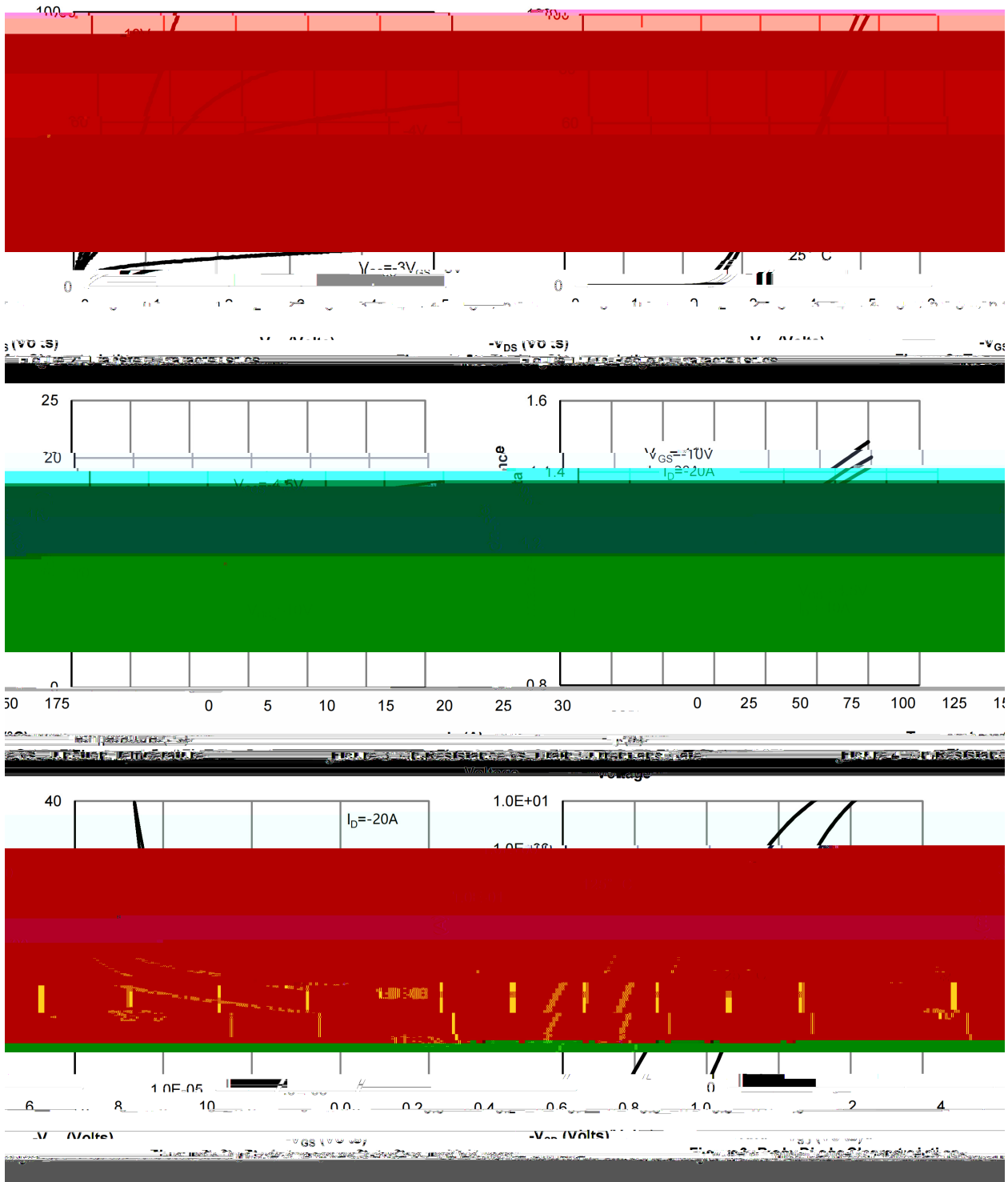


Rev.A Nov.-2022

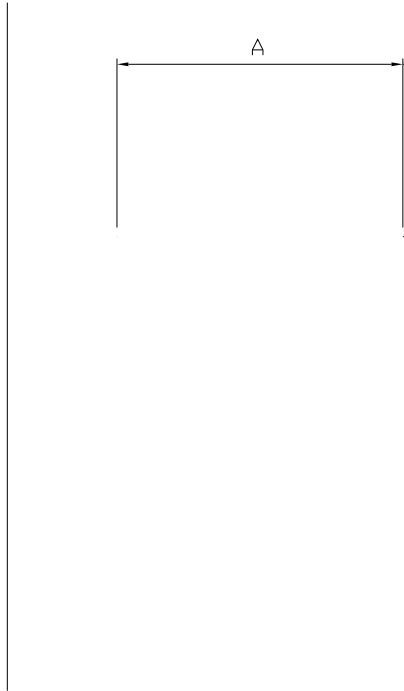
G; =E *2 *8\$/C 'G DFJ

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=-250\mu A$ $V_{GS}=0V$	-30	-36		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30V$ $V_{GS}=0V$			-1	μA
Gate-Body leakage current	I_{GSS}	$V_{DS}=0V$ $V_{GS}=\pm 20V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1.0	-1.7	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V$ $I_D=-20A$		10.5	12	m
		$V_{GS}=-4.5V$ $I_D=-10A$		16.5	18	
Diode Forward Voltage	V_{SD}	$I_S=-1A$ $V_{GS}=0V$			-1.2	V
Gate resistance	R_g	$V_{GS}=0V$ $V_{DS}=0V$ $f=1MHz$		7.5	10	
Input Capacitance	C_{iss}	$V_{GS}=0V$ $V_{DS}=-25V$ $f=1MHz$		2100		pF
Output Capacitance	C_{oss}			340		
Reverse Transfer Capacitance	C_{rss}			210		
Total Gate Charge	$Q_g(10V)$	$V_{GS}=-10V$ $V_{DS}=-15V$ $I_D=-17A$		35		nC
Total Gate Charge	$Q_g(4.5V)$			17		
Gate-Source Charge	Q_{gs}			5.7		
Gate-Drain Charge	Q_{gd}			8.8		
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V$ $V_{DS}=-15V$ $R_L=0.9$ $R_{GEN}=3$		11		ns
Turn-on Rise Time	t_r			7.5		
Turn-off Delay Time	$t_{d(OFF)}$			43.5		
Turn-off Fall Time	t_f			17.5		



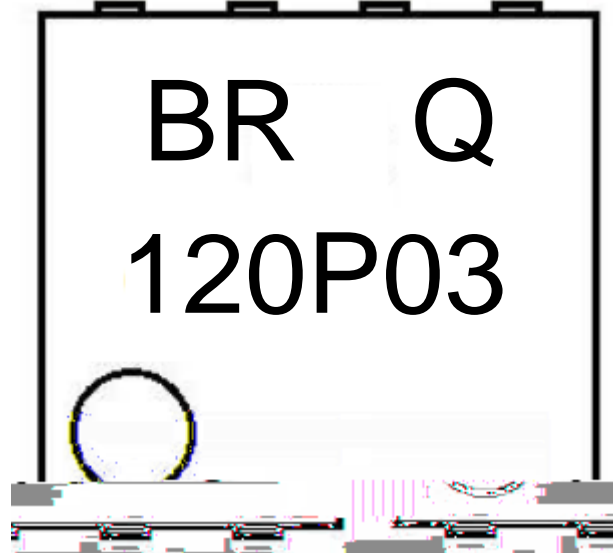
PDFN3X3A-8L

Unit:mm



Dimensions In
Millimeterer
Symbol M

Rev.00 202011



BR

120P03

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Note:

BR: Company Code

120P03: Product Type Code

****: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|-----------|--------------|---|
| 1 | 150 ~ 200 | 60 ~ 120sec; | 1.Preheating:150~200 , Time:60~120sec. |
| 2 | 255..5 | 5..0.5sec; | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 | 2 ~ 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

260..5	10..1 sec.	Temp.:260..5	Time:10...1 sec
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/ REEL

Package Type	Units	Dimension	(unit mm ³)
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